



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Todd O. Bolken

Serial No.: 09/516,080

Filed: March 1, 2000

For: EXPOSED DIE MOLDING
APPARATUS

§
§ Group Art Unit: 2814
§
§
§ Examiner: Unassigned
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§
§ Atty Docket: MICS:0043 FLE/MAN
§ 99-0634

#4
Electronics
JST
10/25/01

Assistant Commissioner
for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING 37 C.F.R. 1.8	
I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date below:	
October 10, 2001	<i>Jennifer Presswood</i>
Date	Jennifer Presswood

Sir:

RESPONSE TO ELECTION REQUIREMENT

In response to the Official Action mailed September 10, 2001, please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel claims 21-46 without prejudice.

REMARKS

Reconsideration of the application as amended is respectfully requested. The Examiner has restricted examination of claims 1-46 in this application. Specifically, the Examiner restricted claims 1-26 and 46 to Group I as being drawn to a microelectronic apparatus, and the Examiner restricted claims 27-45 to Group II as being drawn to a method of packaging. The Examiner further restricted the claims in Group I. Specifically, the Examiner restricted claims 1-

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